KYOCERA KE-300K

Epoxy; Epoxide

KYOCERA Chemical Corporation

Message:

Achieved Fast Cure for In-Line Process as well as Excellent Fillings and Applicable from Insertion Type to Surface Mount Type.
Strong Points
Achieve Good and Necessary Filling in KE-520Series to Apply to Ultra Small Packages.
JEDEC level 1 is Possible in Ultra Small Packages.
Good Adhesion Strength Even after High Temperature Reflow Soldering Process.
Fast Cure Enabling High Productive In-Line Auto Process.
Excellent moldability and show improvement in moldability yield.
Application
Surface Mount Device
TO-92 Type (Insertion Type)
Ultrasmall PKG

General Information		
Features	Fast Cure Good Adhesion Good Moldability	
Uses	Electrical/Electronic Applications	

Physical	Nominal Value	Unit
Specific Gravity	1.80	g/cm³
Spiral Flow	100	cm

Thermal	Nominal Value	Unit
Glass Transition Temperature	180	°C
CLTE - Flow		
-- [1]	1.8E-5	cm/cm/°C
-- [2]	6.7E-5	cm/cm/°C

Uncured Properties	Nominal Value	Unit
Gel Time	0.45	min

NOTE	
1.	Alpha 1
2.	Alpha 2

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WECHAT